

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



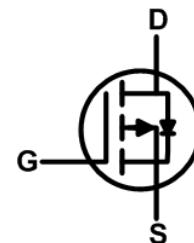
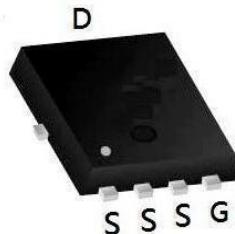
### Product Summary

BVDSS	RDS(ON)	ID
-40V	14mΩ	-25A

### PDFN5060-8L Pin Configuration

#### Description

The XXW25P04F is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The XXW25P04F meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.



#### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	-25	A
$T_C = 100^\circ\text{C}$		-13	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	-90	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	57.8	mJ
Total Power Dissipation	$P_D$	40.3	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

#### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{JA}$	66	°C/W
Thermal Resistance from Junction-to-Case	$R_{JC}$	3.1	°C/W

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-40	-	-	V
Gate-body Leakage current	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$I_{\text{DSS}}$	$V_{\text{DS}} = -40\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	-1	$\mu\text{A}$
$T_J=100^\circ\text{C}$			-	-	-100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.0	-1.5	-2.2	V
Drain-Source On-Resistance <sup>4</sup>	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -20\text{A}$	-	14	19	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -15\text{A}$	-	19	25	
Forward Transconductance <sup>4</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = -10\text{V}, I_D = -20\text{A}$	-	44	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = -20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	2525	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	190	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	172	-	
Gate Resistance	$R_g$	$f = 1\text{MHz}$	-	10	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{\text{GS}} = -10\text{V}, V_{\text{DS}} = -20\text{V}, I_D = -20\text{A}$	-	35	-	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		-	5.5	-	
Gate-Drain Charge	$Q_{\text{gd}}$		-	8	-	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, V_{\text{DD}} = -20\text{V}, R_G = 3\Omega, I_D = -20\text{A}$	-	14.5	-	$\text{ns}$
Rise Time	$t_r$		-	20.2	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	32	-	
Fall Time	$t_f$		-	10	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{\text{SD}}$	$I_S = -20\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	-1.2	V
Continuous Source Current	$T_C=25^\circ\text{C}$	$I_S$	-	-	-25	A

Note :

- Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ .
- The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}= -25\text{V}, V_{\text{GS}}= -10\text{V}, L= 0.1\text{mH}, I_{\text{AS}}= -34\text{A}$ .
- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
- This value is guaranteed by design hence it is not included in the production test.

### Typical Characteristics

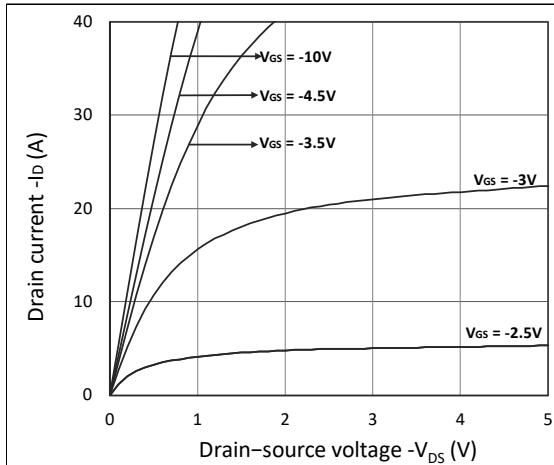


Figure 1. Output Characteristics

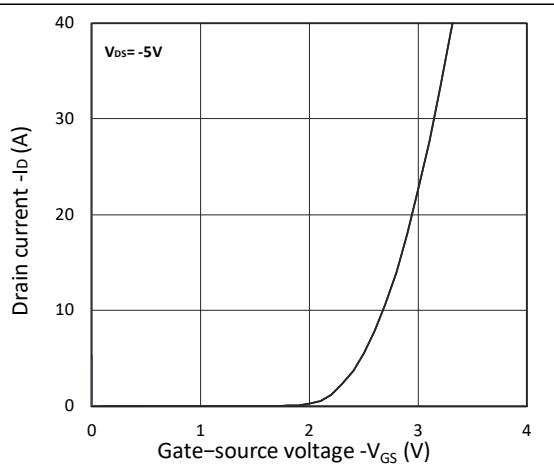


Figure 2. Transfer Characteristics

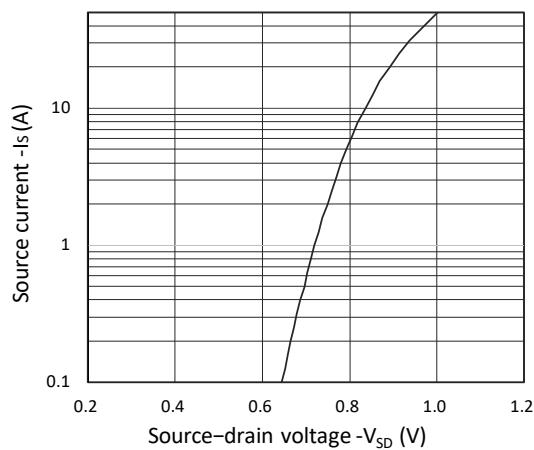


Figure 3. Forward Characteristics of Reverse

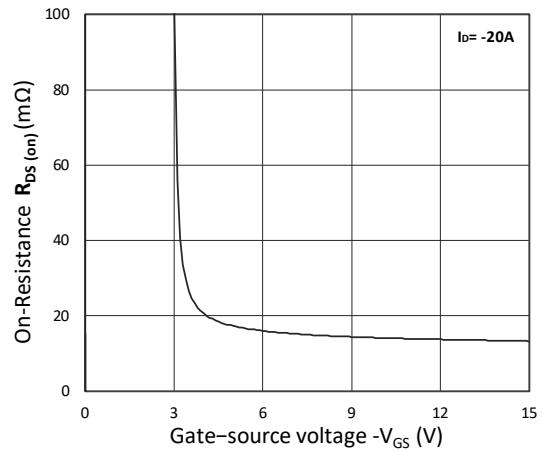


Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$

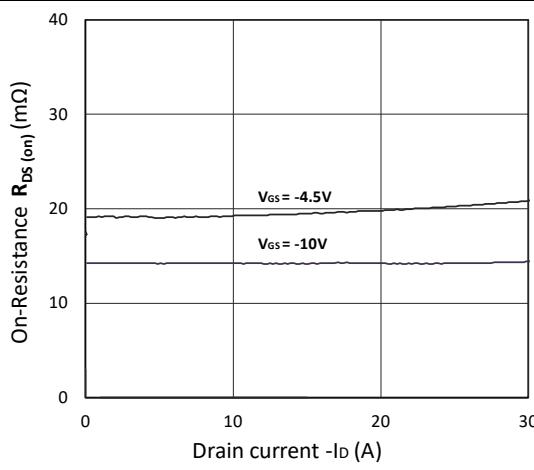


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

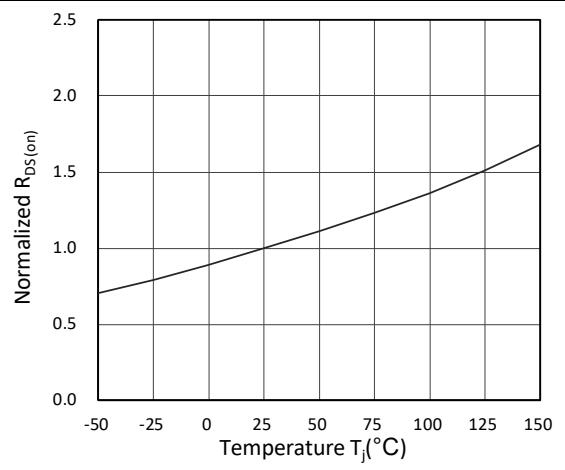


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

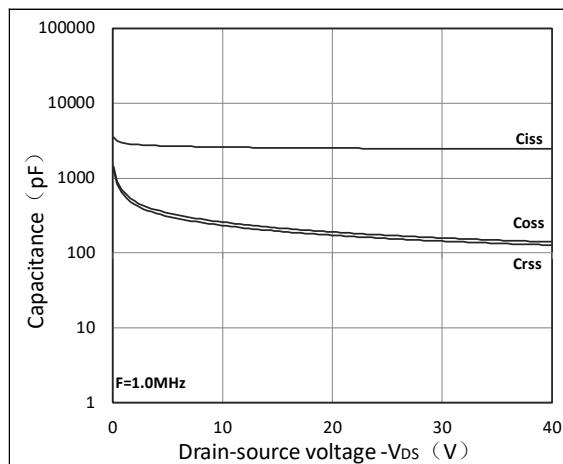


Figure 7. Capacitance Characteristics

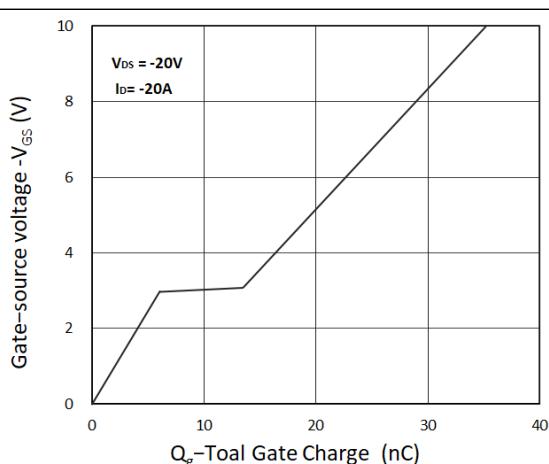


Figure 8. Gate Charge Characteristics

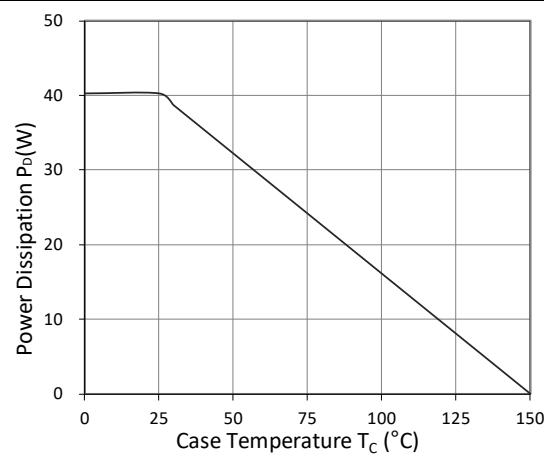


Figure 9. Power Dissipation

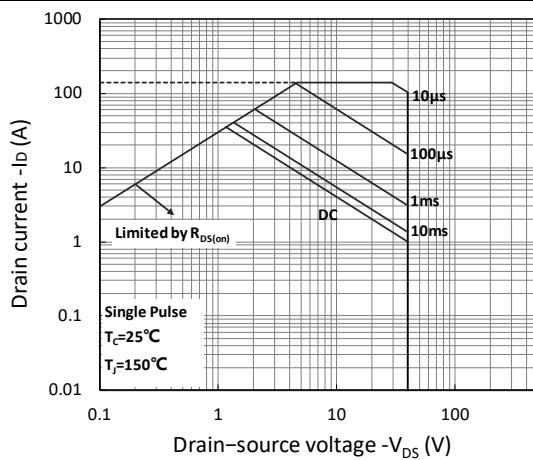


Figure 10. Safe Operating Area

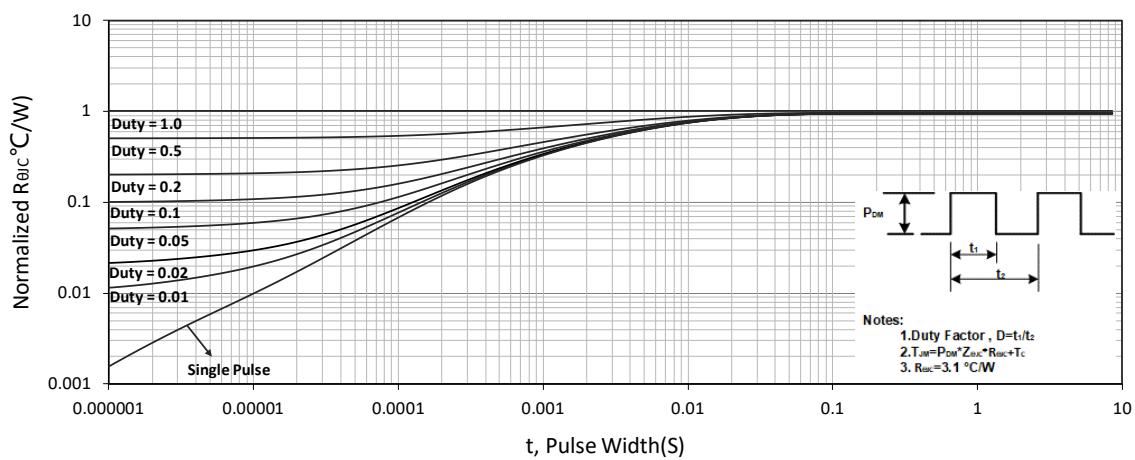
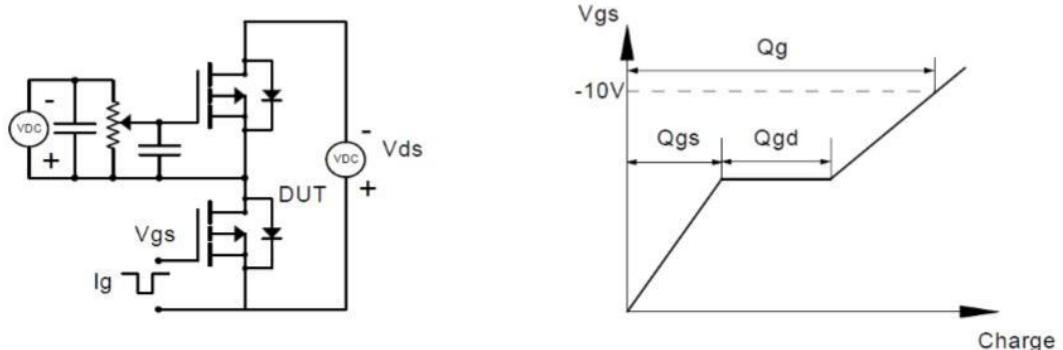
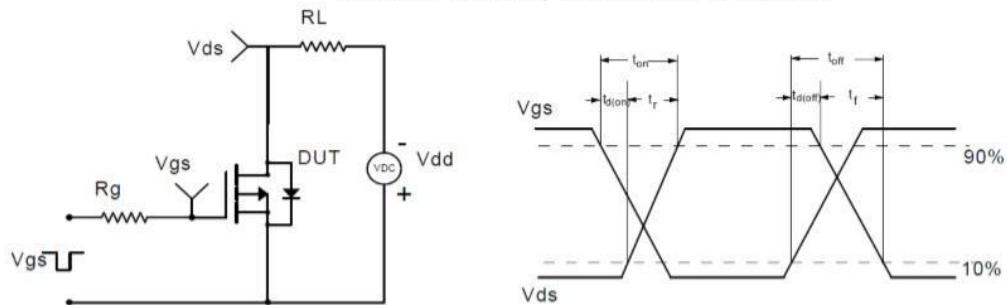
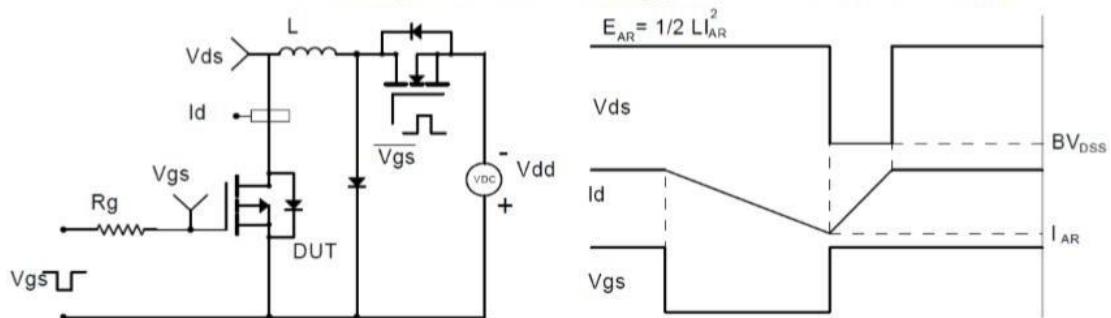
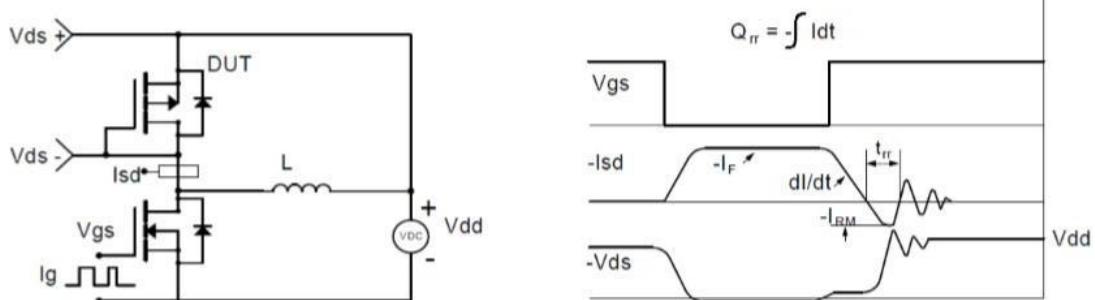
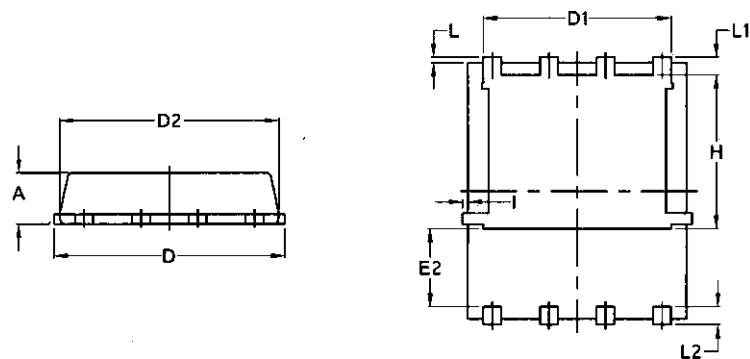
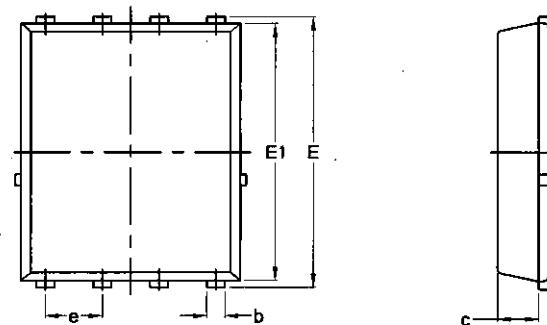


Figure 11. Normalized Maximum Transient Thermal Impedance

**Test Circuit**
**Gate Charge Test Circuit & Waveform**

**Resistive Switching Test Circuit & Waveforms**

**Unclamped Inductive Switching (UIS) Test Circuit & Waveforms**

**Diode Recovery Test Circuit & Waveforms**


## Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070